

ABSTRACT:

The semiconductor device (10) comprises a carrier (30) and a semiconductor element (20), such as an integrated circuit. The carrier (30) is provided with apertures (15), thereby defining connecting conductors (31-33) having side faces (3). Notches (16) are present in the side faces (3). The semiconductor element (20) is enclosed in an encapsulation 5 (40) that extends into the notches (16) in the carrier (30). As a result, the encapsulation (40) is mechanically anchored in the carrier (30). The semiconductor device (10) can be made in a process wherein, after the encapsulating step, no lithographic steps are necessary.

Fig. 1